



AMENDMENTS TO THE CLAIMS

This listing of claims replaces all previous version or listings of the claims:

Claims 1-3. Cancelled.

Claim 4 (Currently amended): A manufacturing method of a multilayer printed wiring board in which at the time of manufacturing each layer of a build-up board composed of a multilayer printed wiring board with an Interstitial Via Hole (IVH) structure includes:

~~a first process step which bonds~~ bonding a metallic foil having electrical conductivity on one side of a sheet-like support substrate ~~and supports possible exfoliation wherein said support substrate supports said metallic foil;~~

~~a second process step which forms~~ forming metallic conductor pieces for said via holes; and

forming patterns in said metallic foil ~~after said first process;~~

~~a third process step which transfers~~ transferring said metallic conductor pieces to a sheet-like insulating resin ~~after said second process~~ by laminating said metallic conductor pieces with said sheet-like insulating resin; and

~~a fourth process step which exfoliates~~ exfoliating said support substrate ~~after said third process.~~

Claim 5 (Currently amended): The manufacturing method of a multilayer printed wiring board according to claim 4, ~~includes a fifth process step in which roughening treatment is performed on~~ further comprising roughening at least the surface of at least said metallic conductor pieces in contact with said insulating resin.

Claim 6 (Currently amended): The manufacturing method of a multilayer printed wiring board according to claim 4 ~~includes a sixth process step in which coating treatment is performed on~~ further comprising coating said metal conductor pieces with a low-temperature diffusion metal.